

*update*

## Refine Search

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### Search Results -

Terms	Documents
(substrate) and (remove insulation)	0

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**Database:**

- US Pre-Grant Publication Full-Text Database
- US Patents Full-Text Database
- US OCR Full-Text Database
- EPO Abstracts Database
- JPO Abstracts Database
- Derwent World Patents Index
- IBM Technical Disclosure Bulletins

**Search:**

Refine Search

Recall Text
Clear
Interrupt

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### Search History

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**DATE:** Monday, October 04, 2004    [Printable Copy](#)    [Create Case](#)

<u>Set Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
side by side			result set
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L46</u>	(substrate) and (remove insulation)	0	<u>L46</u>
<u>L45</u>	L44 and "insulation"	11	<u>L45</u>
<u>L44</u>	(contact thermocouple) and (substrate)	126	<u>L44</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L43</u>	L1 and "substrate"	1	<u>L43</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L42</u>	L41 and "semiconductor wafer"	23	<u>L42</u>
<u>L41</u>	thin film thermocouple	227	<u>L41</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L40</u>	L1 and "extends"	1	<u>L40</u>
<u>L39</u>	L1 and "extends beyond an edge"	0	<u>L39</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L38</u>	junction on substrate	0	<u>L38</u>
<u>L37</u>	L20 and "thin film thermocouple"	42	<u>L37</u>

<u>L36</u>	L35 and "thermocouple"	83	<u>L36</u>
<u>L35</u>	measure substrate temperature	149	<u>L35</u>
<u>L34</u>	junction on bare substrate	0	<u>L34</u>
<u>L33</u>	temperature instrumented	12	<u>L33</u>
<i>DB=USPT; PLUR=YES; OP=ADJ</i>			
<u>L32</u>	6472240.pn.	1	<u>L32</u>
<i>DB=PGPB, USPT, USOC, EPAB, JPAB, DWPI; PLUR=YES; OP=ADJ</i>			
<u>L31</u>	temperature instrumented semiconductor	3	<u>L31</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L30</u>	temperature instrumented semiconductor	1	<u>L30</u>
<i>DB=USPT; PLUR=YES; OP=ADJ</i>			
<u>L29</u>	L20 and "Laof"	0	<u>L29</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L28</u>	L27 and "thermocouple"	3	<u>L28</u>
<u>L27</u>	schuh	132	<u>L27</u>
<i>DB=PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD; PLUR=YES; OP=ADJ</i>			
<u>L26</u>	temperature indicating wafer	2	<u>L26</u>
<u>L25</u>	temperature calibrating wafer	1	<u>L25</u>
<u>L24</u>	L21 and "SenseArray"	0	<u>L24</u>
<u>L23</u>	L21 and "thermocouple"	224	<u>L23</u>
<u>L22</u>	L21 and "hot junction"	1	<u>L22</u>
<u>L21</u>	L20 and "temperature wafer"	350	<u>L21</u>
<u>L20</u>	374/\$	33203	<u>L20</u>
<u>L19</u>	temperature wafer	6691	<u>L19</u>
<u>L18</u>	hot junction formed on substrate	0	<u>L18</u>
<u>L17</u>	L16 and "insulation"	34	<u>L17</u>
<u>L16</u>	forming hot junction	85	<u>L16</u>
<u>L15</u>	L12 and "hot junction"	18	<u>L15</u>
<u>L14</u>	L12 and "hot junction"	18	<u>L14</u>
<u>L13</u>	L12 and "substrate"	13	<u>L13</u>
<u>L12</u>	374/180	149	<u>L12</u>
<u>L11</u>	film extends beyond substrate	2	<u>L11</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L10</u>	L1 and "stretch"	0	<u>L10</u>
<u>L9</u>	L1 and "tension"	0	<u>L9</u>
<u>L8</u>	L1 and "compressive"	0	<u>L8</u>
<u>L7</u>	L1 and "compression"	0	<u>L7</u>
<u>L6</u>	L1 and "tensile"	0	<u>L6</u>
<i>DB=PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD; PLUR=YES; OP=ADJ</i>			
<u>L5</u>	L4 and "thin film"	50	<u>L5</u>
<u>L4</u>	positive strain	803	<u>L4</u>

*DB=PGPB; PLUR=YES; OP=ADJ*

L3 L2 and "positive"  
L2 L1 and "0.006"  
L1 20040101022

0 L3  
1 L2  
1 L1

END OF SEARCH HISTORY